

TITLE OF INVENTION:
SEMICONDUCTOR-PROCESSING TAPE

ABSTRACT

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A semiconductor-processing tape, for use in dividing an adhesive layer along semiconductor chips by expansion, having a base material film, a removable adhesive layer, and an adhesive layer, in this order, wherein the base material film has the stress values in MD and TD at the time of 5%-elongation of 5 MPa or more, the tensile strength values in MD and TD at the time of 5%-elongation of 10 to 30 N/25mm, and the thickness of from 70 to 150 μ m, and wherein the adhesive layer has a thickness of 40 μ m or more and the storage elastic modulus at 25°C of 2000 MPa or less.

15 [Fig. 1]